

# GSM2376

## 60V N-Channel Enhancement Mode MOSFET

### Product Description

GSM2376, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

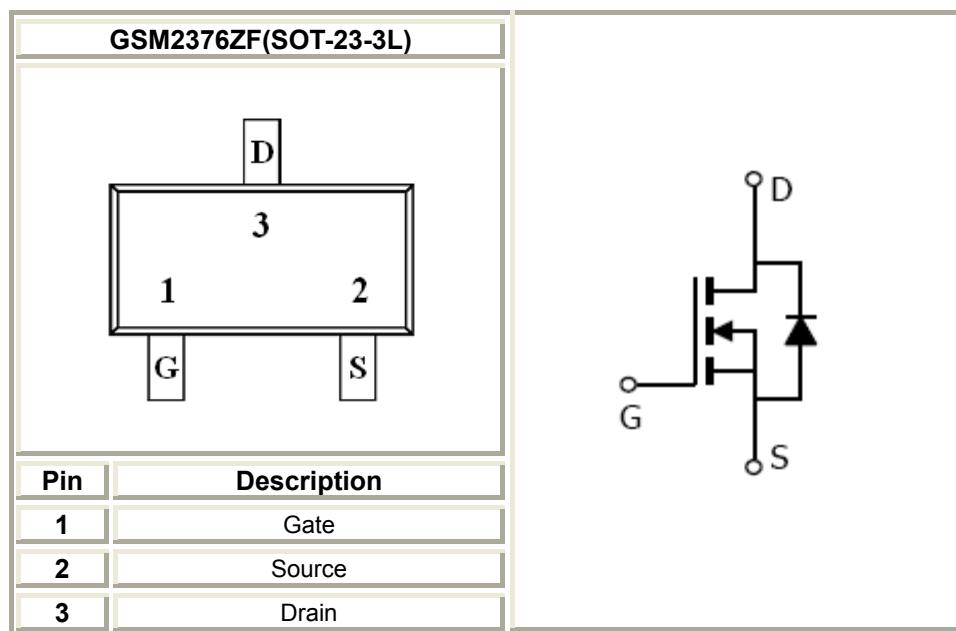
### Features

- 60V/3.6A,  $R_{DS(ON)}=70m\Omega$  @  $V_{GS}=10V$
- 60V/2.8A,  $R_{DS(ON)}=78m\Omega$  @  $V_{GS}=4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design

### Applications

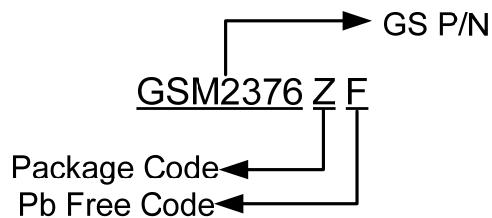
- Portable Equipment
- Battery Powered System
- Net Working System

### Packages & Pin Assignments



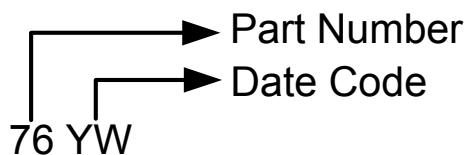
GSM2376

## Ordering Information



Part Number	Package	Quantity Reel
GSM2376ZF	SOT-23-3L	3000 PCS

## Marking Information



## Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate -Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	3.6 2.8
$I_{DM}$	Pulsed Drain Current	10	A
$I_S$	Continuous Source Current(Diode Conduction)	1.6	A
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$	1.25 0.8
$T_J$	Operating Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	120	$^\circ\text{C}/\text{W}$

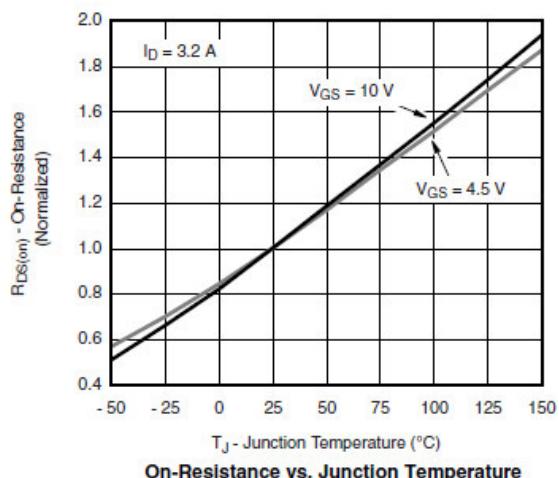
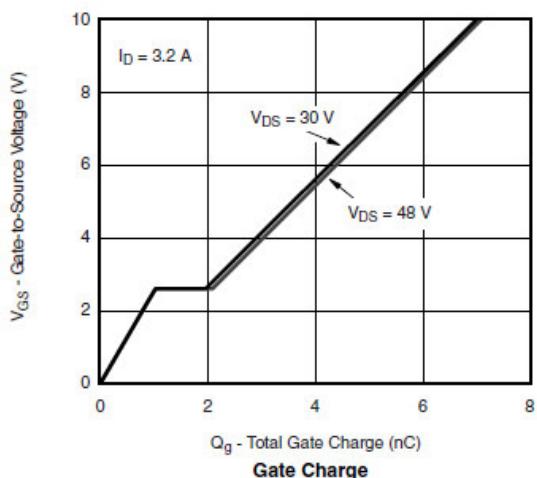
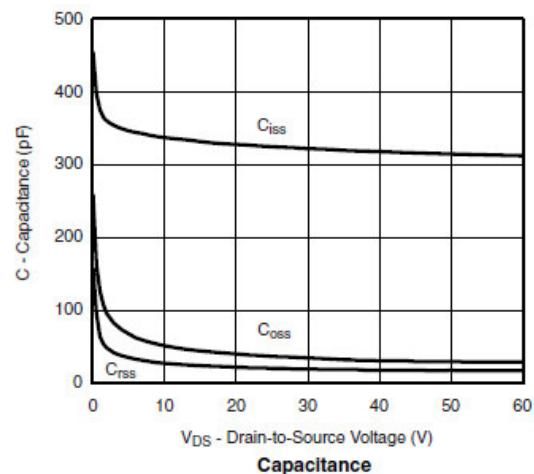
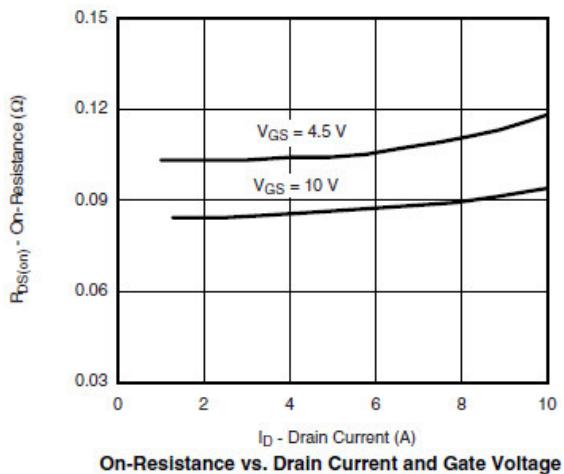
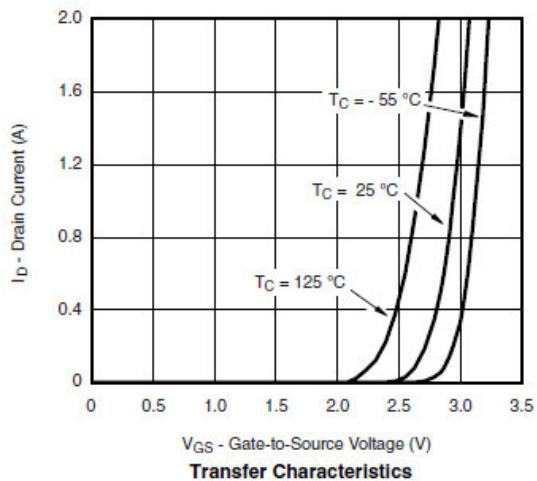
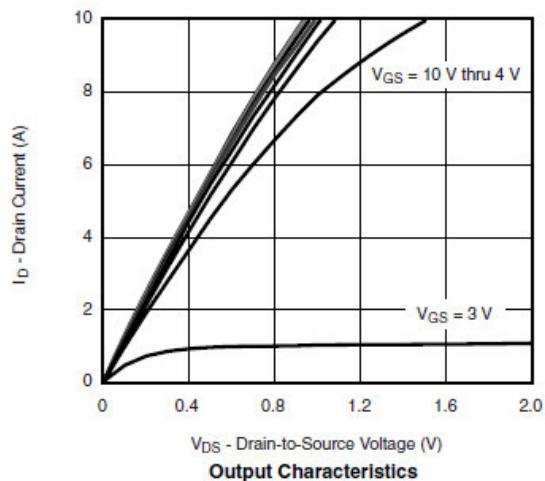
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## Electrical Characteristics

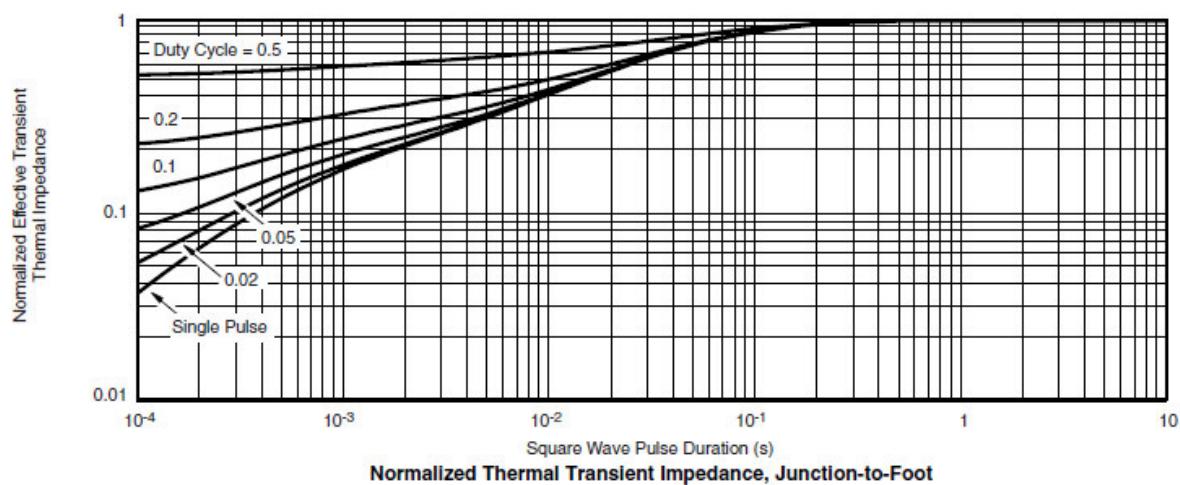
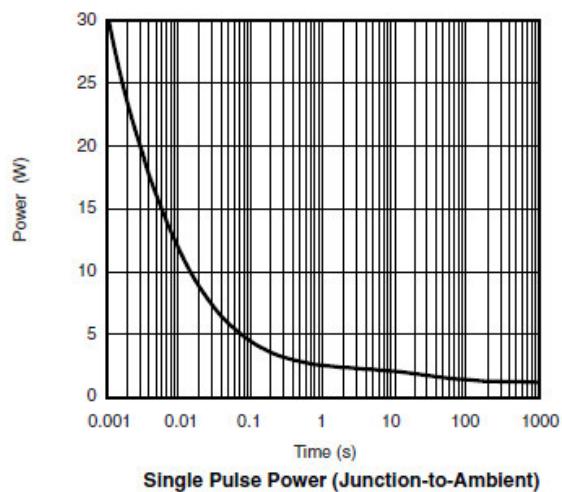
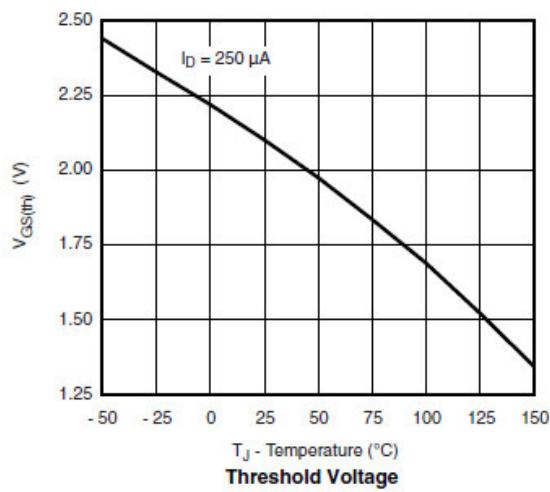
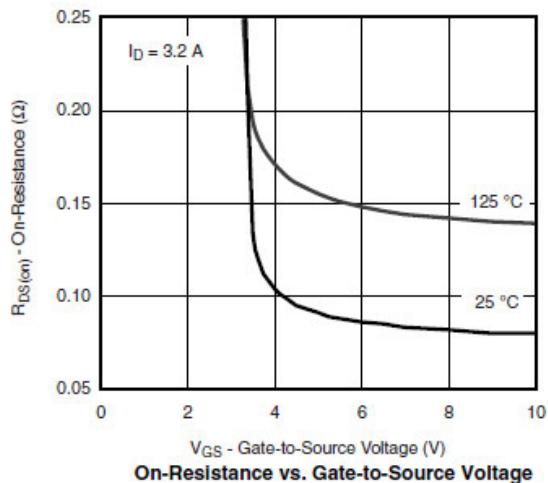
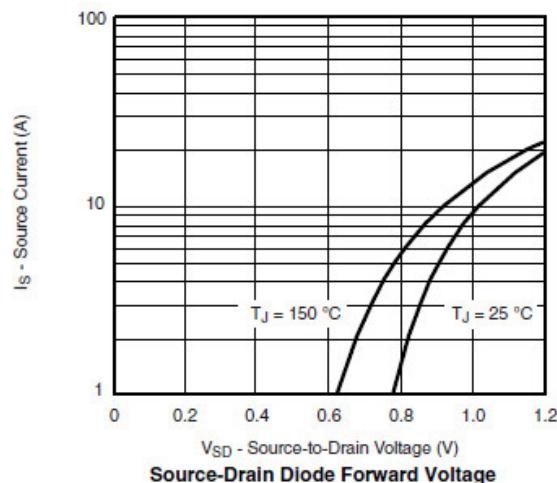
( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	60			V
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.0		2.0	
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 12\text{V}$			$\pm 100$	nA
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$			1	uA
		$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$ $T_J=85^\circ\text{C}$			10	
$I_{\text{D}(\text{on})}$	On-State Drain Current	$V_{\text{DS}} \geq 5\text{V}, V_{\text{GS}}=10\text{V}$	6			A
$R_{\text{DS}(\text{on})}$	Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}, I_D=3.6\text{A}$		55	70	mΩ
		$V_{\text{GS}}=4.5\text{V}, I_D=2.8\text{A}$		60	78	
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=15\text{V}, I_D=3.2\text{A}$		15		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=2.5\text{A}, V_{\text{GS}}=0\text{V}$	0.85	1.2		V
<b>Dynamic</b>						
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=4.5\text{V}, I_D=3.2\text{A}$		6	12	nC
$Q_{\text{gs}}$	Gate-Source Charge				1.5	
$Q_{\text{qd}}$	Gate-Drain Charge				1.2	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		400		pF
$C_{\text{oss}}$	Output Capacitance			40		
$C_{\text{rss}}$	Reverse Transfer Capacitance			20		
$t_{\text{d}(\text{on})}$	Turn-On Time	$V_{\text{DD}}=30\text{V}, R_L=12\Omega, I_D=2.5\text{A}, V_{\text{GEN}}=10\text{V}, R_G=1\Omega$		8	15	ns
$t_r$				10	20	
$t_{\text{d}(\text{off})}$	Turn-Off Time			25	40	
$t_f$				10	20	

## Typical Performance Characteristics

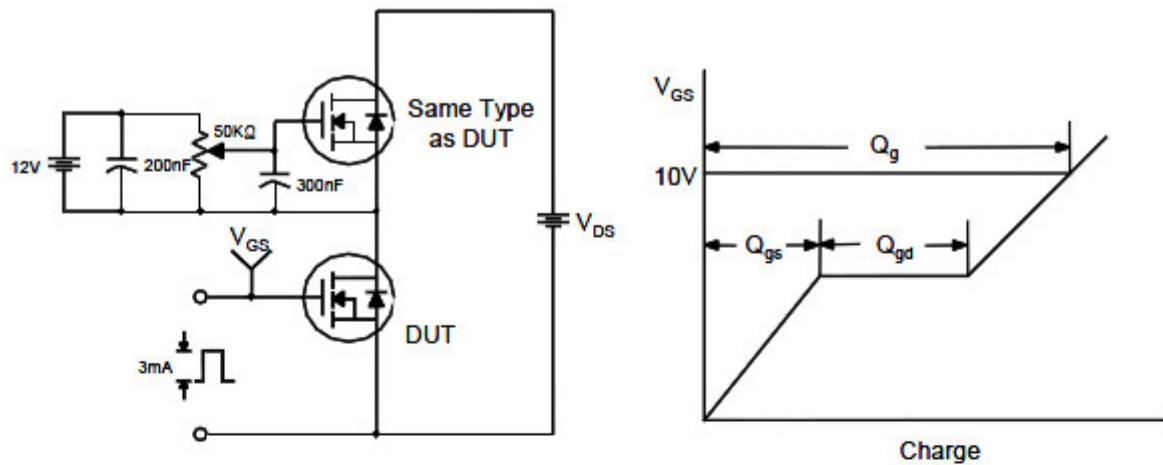


## Typical Performance Characteristics (continue)

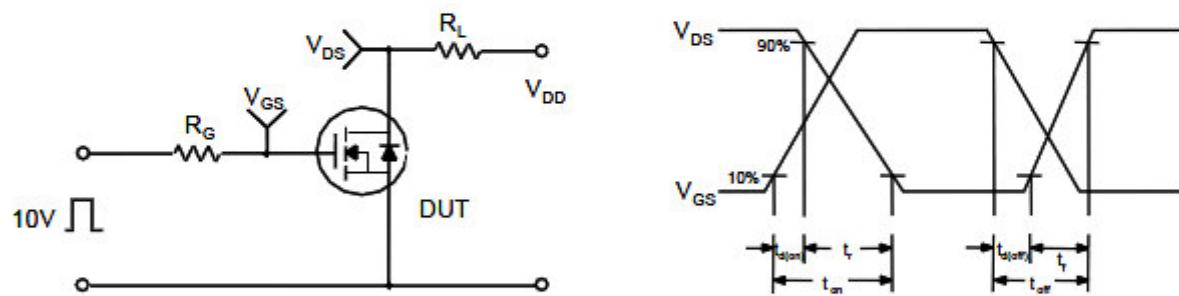


## Typical Performance Characteristics (continue)

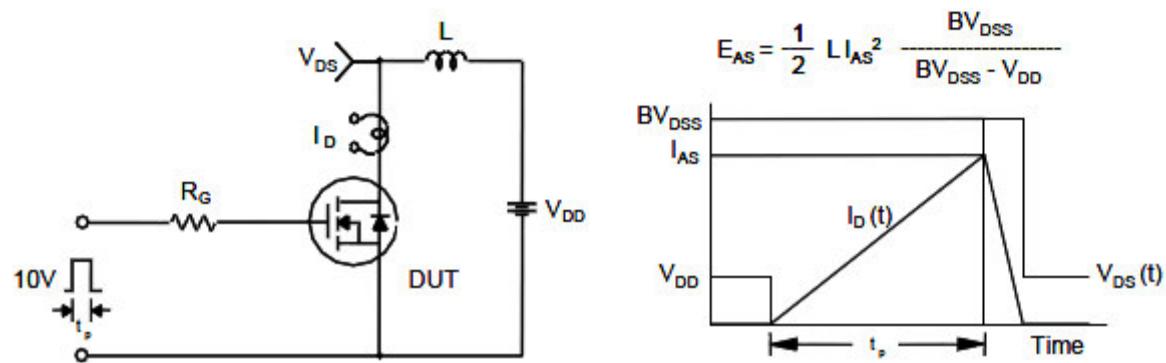
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

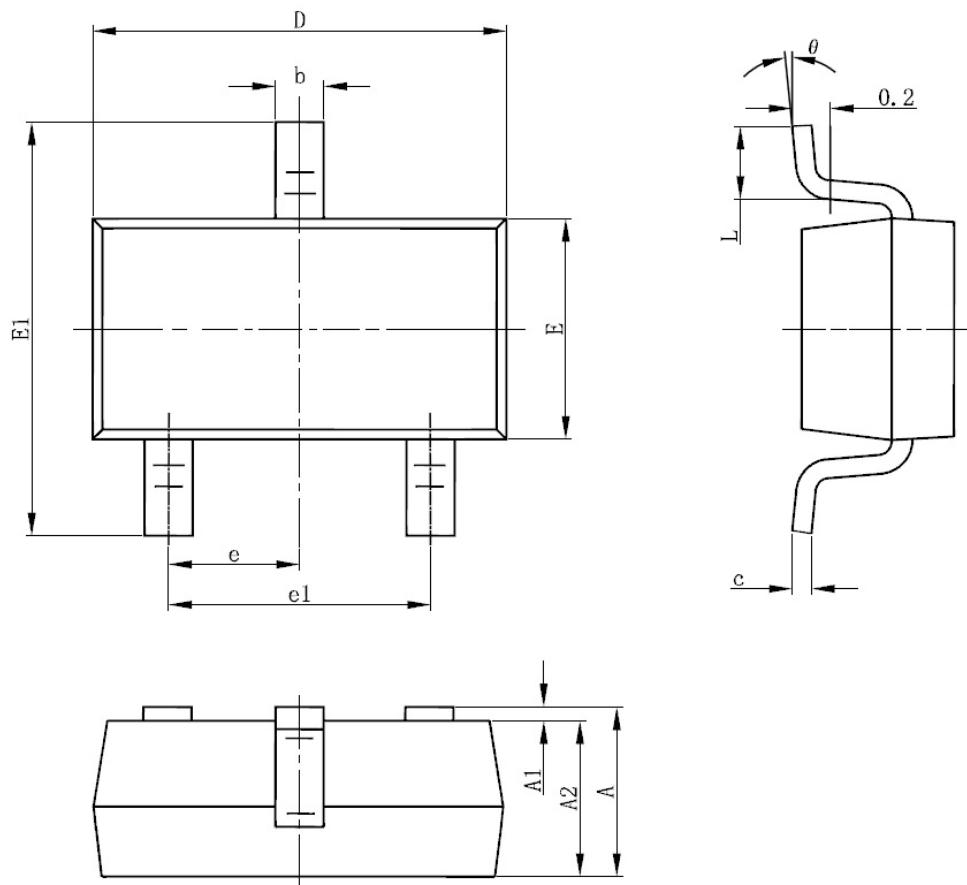


Unclamped Inductive Switching Test Circuit & Waveforms



## Package Dimension

### SOT-23-3L



Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	1.05	1.25	0.041	0.049
A1	0	0.1	0	0.004
A2	1.05	1.15	0.041	0.045
b	0.3	0.4	0.012	0.016
c	0.1	0.2	0.004	0.008
D	2.82	3.02	0.111	0.119
E	1.5	1.7	0.059	0.067
E1	2.65	2.95	0.104	0.116
e	0.950 (TYP)		0.037 (TYP)	
e1	1.8	2	0.071	0.079
L	0.700 REF		0.028 REF	
L1	0.3	0.6	0.012	0.024
θ	0°	8°	0°	8°

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